HZM6.2ZFA

Silicon Epitaxial Planar Zener Diode for Surge Absorb

HITACHI

ADE-208-593(Z)
Rev 0
Nov. 1997

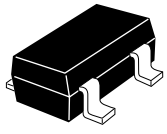
Features

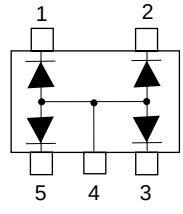
- HZM6.2ZFA has four devices, and can absorb external + and -surge.
- Low capacitance (C=8.5pF max) and can protect ESD of signal line.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HZM6.2ZFA	62Z	MPAK-5

Outline





(Top View)

1 Cathode
2 Cathode
3 Cathode
4 Anode
5 Cathode

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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd [*1]	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note 1. Four device total, See Fig.2.

Electrical Characteristics (Ta = 25°C) [*1]

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V_Z	5.90	—	6.50	V	I_Z = 5 mA, 40ms pulse
Reverse current	I_R	—	—	3	μA	V_R = 5.5V
Capacitance	C	—	8.0	8.5	pF	V_R = 0V, f = 1 MHz
Dynamic resistance	r_d	—	—	60	Ω	I_Z = 5 mA
ESD-Capability [*2]	—	13	—	—	kV	C =150pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes 1. Per one device.
2. Failure criterion ; IR > 3 μA at VR = 5.5V.

Main Characteristic

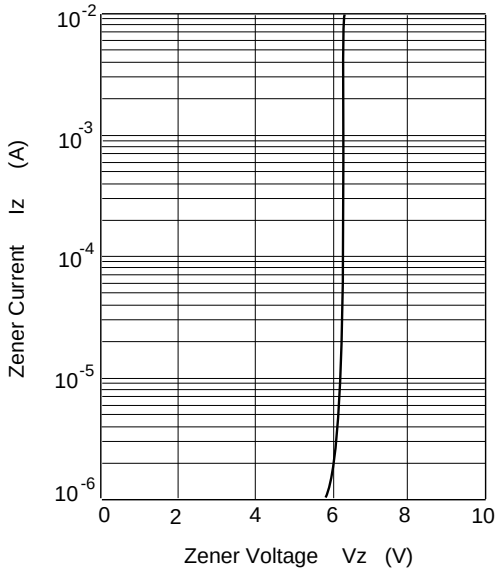


Fig.1 Zener current Vs. Zener voltage

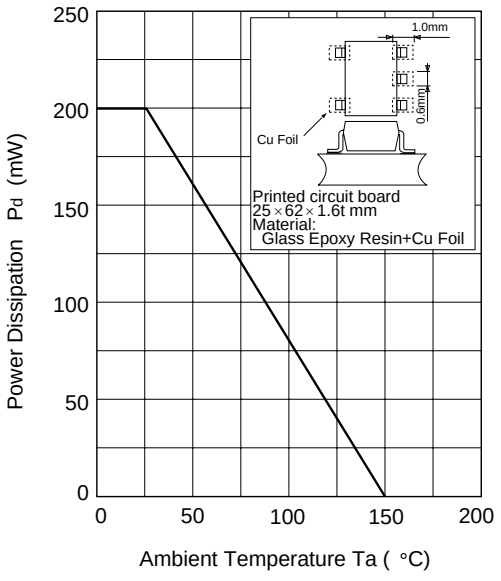


Fig.2 Power Dissipation Vs. Ambient Temperature

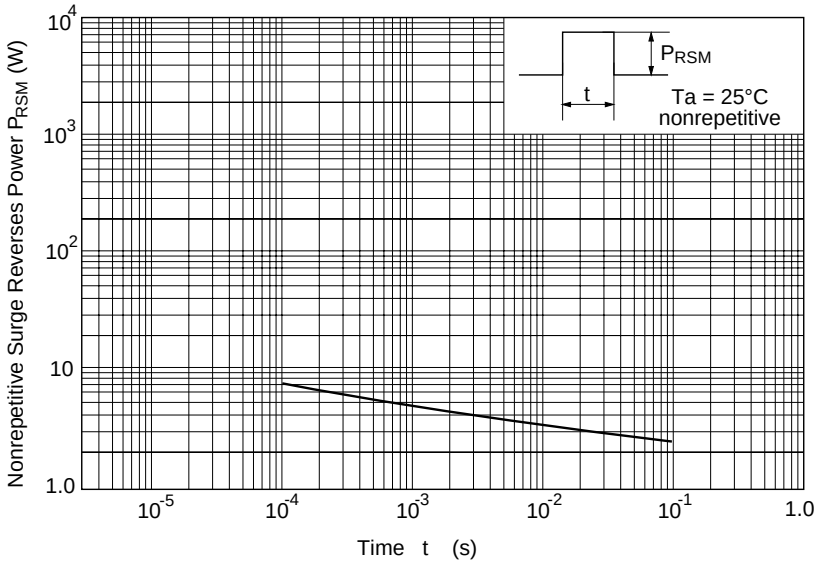


Fig.3 Surge Reverse Power Ratings

Main Characteristic

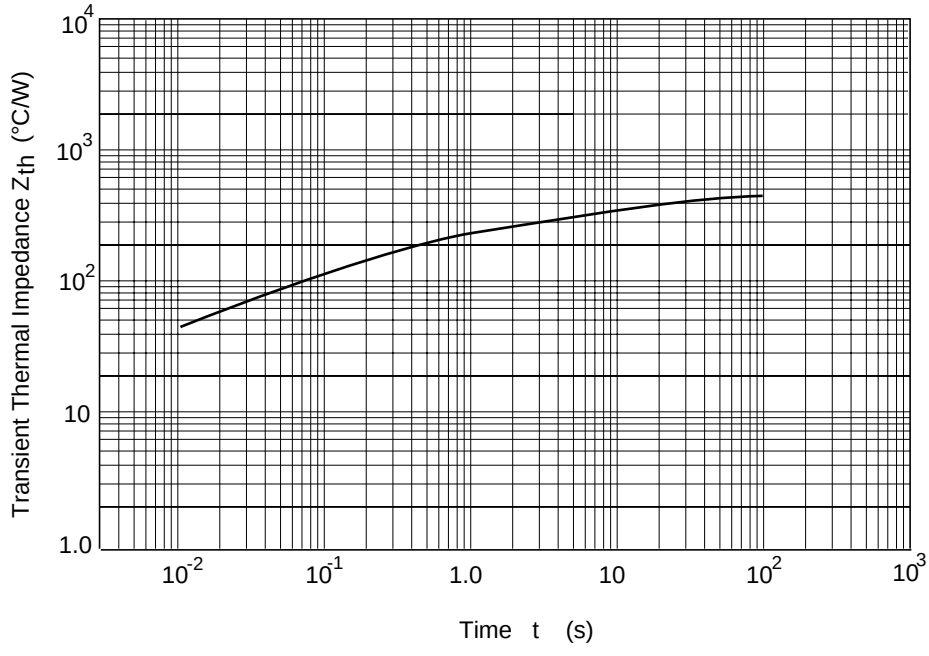
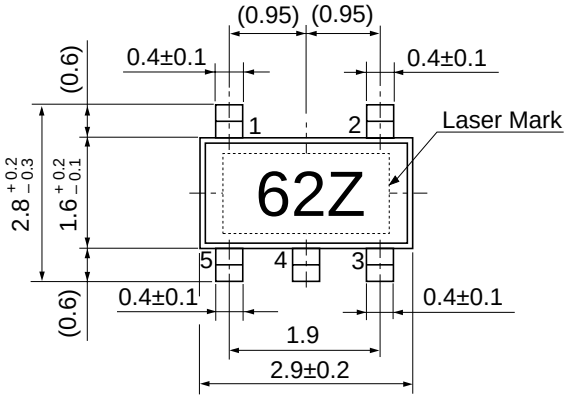
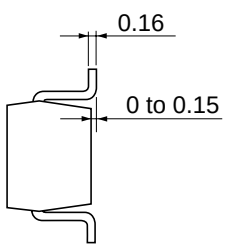


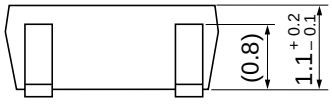
Fig.4 Transient Thermal Impedance

Package Dimensions

Unit : mm







1 Cathode
2 Cathode
3 Cathode
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5 Cathode

Hitachi Code	MPAK-5
JEDEC Code	—
EIAJ Code	—
Weight (g)	0.013

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